

DATASHEET

AX-SIGFOX

Ultra-Low Power, AT Command Controlled, Sigfox Compliant Transceiver IC for Up-Link and Down-Link



Table of Contents

1.	Overview	4
1.1.	Circuit description	4
1.2.	Features	4
1.3.	Applications	5
2.	Block Diagram	6
3.	Pin Function Descriptions	7
3.1.	Pinout Drawing	9
4.	Specifications	o
4.1.	Absolute Maximum Ratings	0
4.2.	DC Characteristics	1
	Supplies1	1
	Typical Current Waveform	2
	Battery Life Examples	3
	Logic1	4
4.3.	AC Characteristics1	4
	TCXO Reference Input	4
	Transmitter	5
	Receiver1	6
	ADC / Temperature Sensor1	6
5.	Command Interface 1	7
5.1.	Serial Parameters: 9600,8,N,1	7
5.2.	Power Modes	7
	Standby1	7
	Sleep1	7
	Deep Sleep1	7
5.3.	AT Commands	8
	Numerical Syntax1	8
	Command Syntax	18

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	Return Codes	. 18
	Examples	.18
	Commands	. 19
	Registers	.24
6.	Application Information	25
6.1.	Typical Application Diagrams	. 25
	Typical Sigfox Application Diagram	. 25
7.	QFN40 Package Information	26
7.1.	Package Outline QFN40 5x7mm	.26
7.2.	QFN40 Soldering Profile	.27
7.3.	QFN40 Recommended Pad Layout	. 28
7.4.	Assembly Process	. 28
	Stencil Design & Solder Paste Application	. 28
8.	Device Versions	30



1. Overview

1.1. Circuit description

AX-Sigfox is an ultra-low power single chip solution for a node on the Sigfox network with both up- and down-link functionality. The AX-Sigfox chip is delivered fully ready for operation and contains all the necessary firmware to transmit and receive data from the Sigfox network in Europe. It connects to the customer product using a logic level RS232 UART. AT commands are used to frames configure send and radio parameters.

1.2. Features

Functionality and Ecosystem

- Sigfox up-link and down-link functionality controlled by AT commands
- The AX-Sigfox IC is part of a whole development and product ecosystem available from AXSEM for any Sigfox requirement. Other parts of the ecosystem include
 - Ready to go AX-Sigfox development kit with fully functional AX-Sigfox module including Sigfox subscription
 - Sigfox Ready certified reference design for the AX-Sigfox IC
 - PIOX by AXSEM Sigfox modules with SMA connector or chip antenna
 - AX-Sigfox-API IC for customers wishing to write their own application software based on the AXSEM Sigfox Library

General Features

- QFN40 4mm x 5mm package
- Supply range 1.8V 3.6V
- -40°C to 85°C
- Temperature sensor
- · Supply voltage measurements
- 10 GPIO pins
 - 4 GPIO pins with selectable voltage measure functionality, differential

- (1V or 10V range) or single ended (1V range) with 10 bit resolution
- 2 GPIO pins with selectable sigma delta DAC output functionality
- 2 GPIO pins with selectable output clock
- 3 GPIO pins selectable as SPI master interface
- Integrated RX/TX switching with differential antenna pins

Power Consumption

- Ultra-low power consumption:
 - Charge required to send a Sigfox OOB packet at 14dBm output power: 0.28 C
 - Deepsleep mode current: 100 nA
 - Sleep mode current: 1.3 μA
 - Standby mode current: 0.5 mA
 - Continuous radio RX-mode at 869.525 MHz : 10 mA
 - Continuous radio TX-mode at 868.130 MHz
 19 mA @ 0 dBm
 49 mA @ 14 dBm

High performance narrow-band Sigfox RF transceiver

- Receiver
 - o Carrier frequency 869.525 MHz
 - o Data-rate 600 bps
 - Sensitivity
 - -126 dBm @ 600bps, 869.525MHz, GFSK
 - 0 dBm maximum input power
- Transmitter
 - o Carrier frequency 868.13 MHz
 - Data-rate 100 bps
 - High efficiency, high linearity integrated power amplifier
 - o Maximum output power 14 dBm
 - Power level programmable in 1dBm steps



1.3. Applications

Sigfox networks up-link and down-link.

Sigfox and Sigfox Ready are registered trademarks of Sigfox SARL.

2. Block Diagram

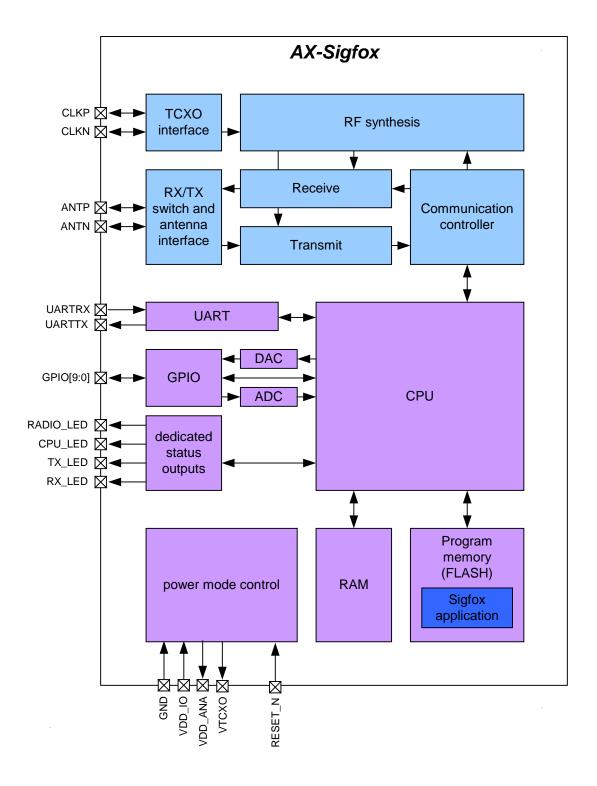


Figure 1 Functional block diagram of the AX-Sigfox



3. Pin Function Descriptions

Symbol	Pin(s)	Туре	Description		
VDD_ANA	1	Р	Analog power output, decouple to neighboring GND		
GND	2	Р	Ground, decouple to neighboring VDD_ANA		
ANTP	3	А	Differential antenna input/output		
ANTN	4	А	Differential antenna input/output		
NC	5	N	Do not connect		
GND	6	Р	Ground, decouple to neighboring VDD_ANA		
VDD_ANA	7	Р	Analog power output, decouple to neighboring GND		
GND	8	Р	Ground		
FILT	9	А	Synthesizer filter		
NC	10	А	Must be connected to pin 11		
NC	11	Α	Must be connected to pin 10		
NC	12	N	Do not connect		
GPIO8	13	I/O/PU	General purpose IO		
GPIO7	14	I/O/PU	General purpose IO, selectable SPI functionality (MISO)		
GPIO6	15	I/O/PU	General purpose IO, selectable SPI functionality (MOSI)		
GPIO5	16	I/O/PU	General purpose IO, selectable SPI functionality (SCK)		
GPIO4	17	I/O/PU	General purpose IO, selectable $\Sigma\Delta$ DAC functionality, selectable clock functionality		
CPU_LED	18	0	CPU activity indicator		
RADIO_LED	19	0	Radio activity indicator		
VTCXO	20	0	TCXO power		
GPIO9	21	I/O/PU	General purpose IO, wakeup from deep sleep		
UARTTX	22	0	UART transmit		
UARTRX	23	I/PU	UART receive		
RX_LED	24	0	Receive activity indicator		
TX_LED	25	0	Transmit activity indicator		
NC	26	PD	Do not connect		
RESET_N	27	I/PU	Optional reset pin Internal pull-up resistor is permanently enabled, nevertheless it is recommended to connect this pin to VDD_IO if it is not used.		
GND	28	Р	Ground		
VDD_IO	29	Р	Unregulated power supply		
GPIO0	30	I/O/A/PU	General purpose IO, selectable ADC functionality, selectable $\Sigma\Delta$ DAC functionality, selectable clock functionality		
GPIO1	31	I/O/A/PU	General purpose IO, selectable ADC functionality		
GPIO2	32	I/O/A/PU	General purpose IO, selectable ADC functionality		
NC	33	N	Do not connect		
NC	34	N	Do not connect		





Symbol	Pin(s)	Туре	Description
GPIO3	35	I/O/A/PU	General purpose IO, selectable ADC functionality
VDD_IO	36	Р	Unregulated power supply
NC	37	N	Connect to Ground
NC	38	N	Connect to Ground
CLKN	39	А	TCXO interface
CLKP	40	А	TCXO interface
GND	Center pad	Р	Ground on center pad of QFN, must be connected

All digital inputs are Schmitt trigger inputs, digital input and output levels are LVCMOS/LVTTL compatible. Pins GPIO[3:0] must not be driven above VDD_IO, all other digital inputs are 5V tolerant. All GPIO pins and UARTRX start up as input with pull-up.

Pin	Possible GPIO modes
GPIO0	0,1,Z,U,A,T
GPIO1	0,1,Z,U,A
GPIO2	0,1,Z,U,A
GPIO3	0,1,Z,U,A
GPIO4	0,1,Z,U,T
GPIO5	0,1,Z,U
GPIO0	0,1,Z,U
GPIO1	0,1,Z,U
GPIO2	0,1,Z,U
GPIO3	0,1,Z,U

0 = pin drives

1 = not to be connected

Z = pin is high impedance input U = pin is input with pull-up

A = pin is analog input

T = pin is driven by clock or DAC



3.1. Pinout Drawing

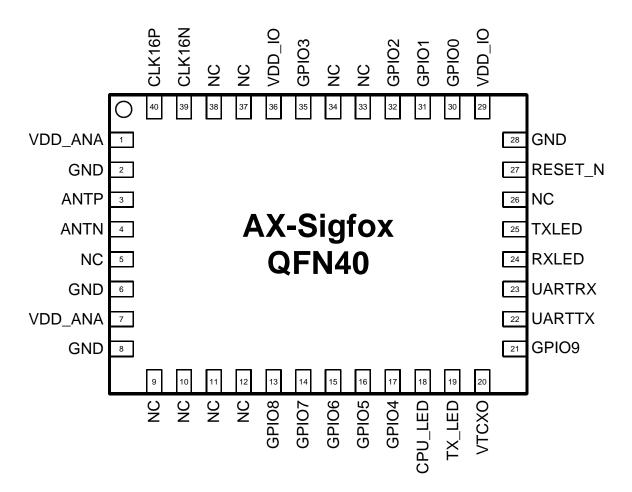


Figure 2 Pinout drawing (Top view)



4. Specifications

4.1. Absolute Maximum Ratings

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device.

This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied.

Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

SYMBOL	DESCRIPTION	CONDITION	MIN	MAX	UNIT
VDD_IO	Supply voltage		-0.5	5.5	V
IDD	Supply current			200	mA
P _{tot}	Total power consumption			800	mW
P _i	Absolute maximum input power at receiver input	ANTP and ANTN pins in RX mode		10	dBm
I _{I1}	DC current into any pin except ANTP, ANTN		-10	10	mA
I ₁₂	DC current into pins ANTP, ANTN		-100	100	mA
Io	Output Current			40	mA
V _{ia}	Input voltage ANTP, ANTN pins		-0.5	5.5	V
	Input voltage digital pins		-0.5	5.5	V
V _{es}	Electrostatic handling	HBM	-2000	2000	V
T _{amb}	Operating temperature		-40	85	°C
T _{stg}	Storage temperature		-65	150	°C
T _j	Junction Temperature			150	°C



4.2. DC Characteristics

Supplies

SYM	DESCRIPTION	CONDITION	MIN	ТҮР	мах	UNIT
	all current and energy values unless otherwise s int Reference Design.	specified are for the hardware configuration describ	ed in the	AX-Sigfox	c Applicati	on Note:
T _{AMB}	Operational ambient temperature		-40	27	85	°C
VDD _{IO}	I/O and voltage regulator supply voltage		1.8	3.0	3.6	V
VDD _{IO_R1}	I/O voltage ramp for reset activation; Note 1	Ramp starts at VDD_IO≤0.1V	0.1			V/ms
VDD _{IO_R2}	I/O voltage ramp for reset activation; Note 1	Ramp starts at 0.1V <vdd_io<0.7v< td=""><td>3.3</td><td></td><td></td><td>V/ms</td></vdd_io<0.7v<>	3.3			V/ms
I _{DS}	Deep sleep mode current	AT\$P=2		100		nA
I _{SLP}	Sleep mode current	AT\$P=1		1.3		μΑ
I _{STDBY}	Standby mode current			0.5		mA
I _{RX_CONT}	Current consumption continuous RX	AT\$SR=1,1,-1		10		mA
Q _{SFX_OOB_0}	Energy to send a Sigfox out of band message, OdBm	AT\$SO		0.12		С
Q _{SFX_BIT_0}	Energy to send a bit, 0dBm	AT\$SB=0		0.08		С
Q _{SFX_BITDL_0}	Energy to send a bit with downlink receive, 0dBm	AT\$SB=0,1		0.14		С
Q _{SFX_LFR_0}	Energy to send the longest possible Sigfox frame (12 byte), 0dBm	AT\$SF=00112233445566778899aabb		0.27		С
Q _{SFX_LFRDL_0}	Energy to send the longest possible Sigfox frame (12 byte) with downlink receive, OdBm	AT\$SF=00112233445566778899aabb,1		0.27		С
Q _{SFX_OOB_14}	Energy to send a Sigfox out of band message, 14dBm	AT\$SO		0.28		С
Q _{SFX_BIT_14}	Energy to send a bit, 14dBm	AT\$SB=0		0.20		С
Q _{SFX_BITDL_14}	Energy to send a bit with downlink receive, 14dBm	AT\$SB=0,1		0.35		С
Q _{SFX_LFR_14}	Energy to send the longest possible Sigfox frame (12 byte), 14dBm	AT\$SF=00112233445566778899aabb		0.39		С
Q _{SFX_LFRDL_14}	Energy to send the longest possible Sigfox frame (12 byte) with downlink receive, 14dBm	AT\$SF=00112233445566778899aabb,1		0.46		С
I _{TXMODOAVG}	Modulated Transmitter Current, Notes 3, 4	Pout=0 dBm; average		19.0		mA
I _{TXMOD14AVG}	Modulated Transmitter Current, Notes 3, 4	Pout=14 dBm; average		49.0		mA

Notes :

- .

 1. If VDD_IO ramps cannot be guaranteed, an external reset circuit is recommended, see the AX8052 Application Note: Power On Reset
- Digital circuitry is functional down to typically 1 V.
- 3. The output power of the AX-Sigfox can be programmed in 1 dB steps from 0 dBm 14 dBm. Current consumption values are given for a matching network that is optimized for 14 dBm output. 0 dBm transmission with typically 10 mA can be achieved with other networks that are optimized for 0 dBm operation.
- 4. Values in dBm are typical, the matching network is optimized for 14 dBm



Typical Current Waveform

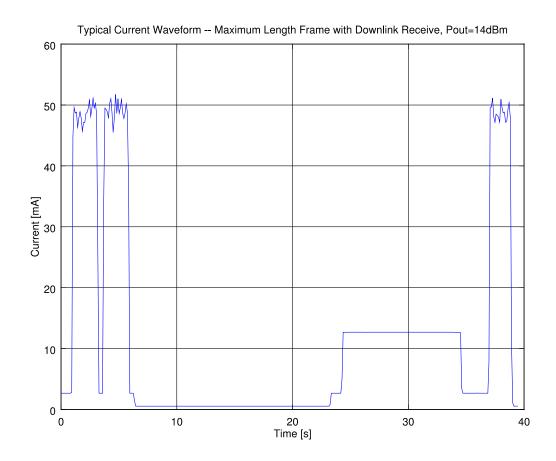


Figure 3 Typical current waveform for a maximum length frame with downlink receive at 14 dBm output power



Battery Life Examples

Scenario 1:

- CR2032 coin cell battery
- One OOB frame transmitter per day at Pout=0 dBm
- Device in Sleep
- Neglecting battery self discharge

CR2032 capacity	225 mAh * 3600 s/h	810 C
Sleep charge per day	1.3 μA * 86400s	0.11 C/day
OOB frame transmission		0.12 C/day
Total Charge consumption		0.23 C/day
Battery life		9.6 Years

Scenario 2:

- 2 AAA Alkaline batteries in series
- One OOB frame transmitter per day at Pout=14 dBm
- Four maximum length frames with downlink receive per day at Pout=14 dBm
- Device in Sleep
- Neglecting battery self discharge

2 AAA alkaline capacity	1500 mAh * 3600 s/h	5400 C
Sleep charge per day	1.3 μA * 86400s	0.11 C/day
OOB frame transmission		0.28 C/day
Frame transmission with downlink	4 * 0.46 C/day	1.84 C/day
Total Charge consumption		2.26 C/day
Battery life		6.5 Years



Logic

SYMBOL	DESCRIPTION	CONDITION	MIN	ТҮР	MAX	UNIT
DIGITAL I	NPUTS					
V_{T+}	Schmitt trigger low to high threshold point			1.55		V
V _{T-}	Schmitt trigger high to low threshold point	VDD_IO = 3.3V		1.25		V
V _{IL}	Input voltage, low				0.8	V
V _{IH}	Input voltage, high		2.0			V
V _{IPA}	Input voltage range, GPIO[3:0]		-0.5		VDD_IO	V
V _{IPBC}	Input voltage range, GPIO[9:4], UARTRX		-0.5		5.5	V
IL	Input leakage current		-10		10	μΑ
R _{PU}	Programmable Pull-Up Resistance			65		kΩ
DIGITAL O	DUTPUTS		•	•	•	
I _{OH}	Output Current, high Ports GPIO[9:0], UARTTX, TXLED, RXLED, TXLED, CPULED	V _{OH} = 2.4V	8			mA
I _{OL}	Output Current, low GPIO[9:0], UARTTX, TXLED, RXLED, TXLED, CPULED	V _{OL} = 0.4V	8			mA
l _{oz}	Tri-state output leakage current		-10		10	μA

4.3. AC Characteristics

TCXO Reference Input

SYMBOL	DESCRIPTION	CONDITION	MIN	ТҮР	MAX	UNIT
f _{TCXO}	TCXO frequency	A passive network between the TCXO output and the pins CLKP and CLKN is required. For detailed TCXO network recommendations depending on the TCXO output swing refer to the AX5043 Application Note: Use with a TCXO Reference Clock. For TCXO recommendations see the Ax-Sigfox Application Note: Sigfox Compliant Reference Design		48		MHz



Transmitter

SYMBOL	DESCRIPTION	CONDITION	MIN	ТҮР	MAX	UNIT			
	Conditions for transmitter specifications unless otherwise specified with the antenna network from AX-Sigfox Application Note: Sigfox Compliant Reference Design and at 868.130 MHz.								
SBR	Signal bit rate			100		bps			
PTX _{min}	Lowest Transmitter output power	AT\$CW=868130000,1,0		0		dDm			
PTX _{max}	Highest Transmitter output power	AT\$CW=868130000,1,14		14		dBm			
PTX _{step}	Programming step size output power			1		dB			
dTX _{temp}	Transmitter power variation vs. temperature	-40 °C to +85 °C		+/- 0.5		dB			
dTX _{Vdd}	Transmitter power variation vs. VDD_IO	1.8 to 3.6 V		+/- 0.5		dB			
PTX _{harm2}	Emission @ 2 nd harmonic			-51					
PTX _{harm3}	Emission @ 3 rd harmonic			-63		dBc			
PTX _{harm4}	Emission @ 4 th harmonic			-84					

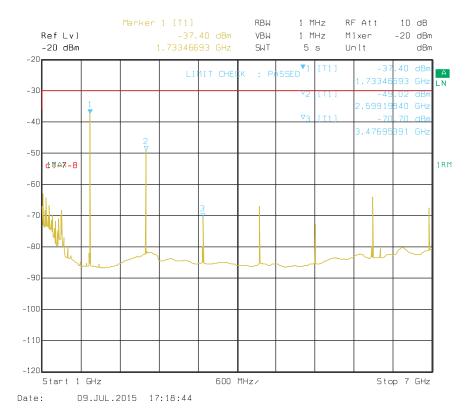


Figure 4 Typical spectrum with harmonics at 14 dBm output power



Receiver

SYM	DESCRIPTION	CONDITION	MIN	TYP	MAX	UNIT
	Conditions for transmitter specifications unless otherwise specified with the antenna network from AX-Sigfox Application Note: Sigfox Compliant Reference Design and at 869.525 MHz.				pliant	
SBR	Signal bit rate			600		bps
IS _{BER868}		AT\$SB=x,1, AT\$SF=x,1, AT\$SR PER < 0.1		-126		dBm
BLK ₈₆₈	Blocking at +/- 10MHz offset	Channel/Blocker @ PER = 0.1, wanted signal level is +3 dB above the typical sensitivity, the blocker signal is CW		78		dB

ADC / Temperature Sensor

SYMBOL	DESCRIPTION	CONDITION	MIN	TYP	MAX	UNIT
ADCRES	ADC resolution			10		Bits
V _{ADCREE}	ADC reference voltage		0.95	1	1.05	V
Z _{ADC00}	Input capacitance		0.75	'	2.5	pF
DNL	· · ·			+/- 1	2.5	LSB
	Differential nonlinearity					
INL	Integral non inearity			+/- 1		LSB
OFF	Offset			3		LSB
GAIN_ERR	Gain error			0.8		%
ADC in Diff	erential Mode					
V _{ABS_DIFF}	Absolute voltages & common mode voltage in differential mode at each input		0		VDD_IO	V
V _{FS_DIFF01}	Full swing input for differential	Gain x1	-500		500	mV
V _{FS_DIFF10}	signals	Gain x10	-50		50	mV
ADC in Sing	gle Ended Mode	1	I .		I	
$V_{\text{MID_SE}}$	Mid code input voltage in single ended mode			0.5		V
V _{IN_SE00}	Input voltage in single ended mode		0		VDD_IO	V
V _{FS_SE01}	Full swing input for single ended signals	Gain x1	0		1	V
Temperatu	re Sensor	•			1	•
T _{RNG}	Temperature range	AT\$T?	-40		85	°C
T _{ERR_CAL}	Temperature error	AT\$T?	-2		+2	°C

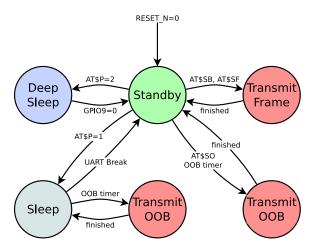


5. Command Interface

5.1. Serial Parameters: 9600,8,N,1

The **AX-Sigfox** uses the UART (pins UARTTX, UARTRX) to communicate with a host and uses a bitrate of **9600 baud**, no parity, 8 data bits and one stop bit.

5.2. Power Modes



Standby

After Power-Up and after finishing a SIGFOX transmission, **AX-Sigfox** enters Standby mode. In Standby mode, **AX-Sigfox** listens on the UART for commands from the host. Also, OOB frames are transmitted whenever the OOB timer fires. To conserve power, the **AX-Sigfox** can be put into Sleep or turned off (Deep Sleep) completely.

Sleep

The command AT\$P=1 is used to put the AX-Sigfox into Sleep mode. In this mode, only the wakeup timer for out-of-band messages is still running. To wake the AX-Sigfox up from Sleep mode toggle the serial UARTRX pin, e.g. by sending a break (break is an RS232 framing violation, i.e. at least 10 bit durations low). When an Out of Band (OOB) message is due, AX-Sigfox automatically wakes up to transmit the message, and then returns to Sleep mode.

Deep Sleep

In Deep Sleep mode, the **AX-Sigfox** is completely turned off and only draws negligible leakage current. Deep Sleep mode can be activated with **AT\$P=2**. To wake-up from Deep Sleep mode, GPIO9 is pulled to GND.



When using Deep Sleep mode, keep two things in mind:

Everything is turned off, timers are not running at all and all settings will be lost (use AT\$WR to save settings to flash before entering Deep Sleep mode). Out-of-band messages will therefore not be sent. The pins states are frozen in Deep Sleep mode. The user must ensure that this will not result in condition which would draw a lot of current.

5.3. AT Commands

Numerical Syntax

```
hexdigit
             ::=
                   [0-9A-Fa-f]
hexnum
             ::=
                   "0x" hexdigit+
             ::=
                   "0" | [1-9] [0-9]*
decnum
                   "0" [0-7]+
octnum
            ::=
binnum
            ::=
                   "0b" [01]+
             ::=
                   [01]
bit
             ::=
                   w<sub>-1"</sub>
optnum
frame
             ::=
                   (hexdigit hexdigit)+
uint
             ::=
                   hexnum | decnum | octnum | binnum
            ::=
                   uint | optnum
uint_opt
```

Command Syntax

A command starts with 'AT' (everything is case sensitive!), continues with the actual command followed by parameters (if any) and ends with any kind of whitespace (space, tab, newline etc.)

If incorrect syntax is detected ("parsing error") all input is ignored up until the next whitespace character.

Also note that any number can be entered in any format (Hexadecimal, Decimal, Octal and binary) by adding the corresponding prefix ('0x', '0', '0b'). The only exception is the 'Send Frame' command (AT\$SF) which expects a list of hexadecimal digits without any prefix.

Return Codes

A successful command execution is indicated by sending 'OK'. If a command returns a value (e.g. by querying a register) only the value is returned.

Examples

Bold text is sent to **AX-Sigfox**.

```
AT$I=0
AXSEM AT Command Interface
```

Here, we execute command 'I' to query some general information.

```
AT$SF=aabb1234
```





This sends a Sigfox frame containing { 0x00 : 0x11 : 0x22 : 0x33 : 0x44 }, then waits for a downlink response telegram, which in this example contains { 0xAA : 0xBB : 0xCC : 0xDD }.

AT\$SF=0011223344,1

OK

RX=AA BB CC DD

This sends a Sigfox frame containing $\{ 0xAA : 0xBB : 0x12 : 0x34 \}$ without waiting for a response telegram.

AT\$CB=0xAA,1

OK

The 'CB' command sends out a continuous pattern of bits, in this case 0xAA = 0b10101010.

AT\$P=1

OK

This transitions the device into sleep mode. Out-of-band transmissions will still be triggered. The UART is powered down. The device can be woken up by a low level on the UART signal, i.e. by sending break.

Commands

Command	Name	Description
AT	Dummy command	Just returns 'OK' and does nothing else. Can be used to check communication.
AT\$SB=bit[,bit]	Send bit	Send a bit status (0 or 1). Optional bit flag indicates if AX-Sigfox should receive a downlink frame.
AT\$SF=frame[,bit]	Send frame	Send payload data, 1 to 12 bytes. Optional bit flag indicates if AX-Sigfox should receive a downlink frame.
AT\$SO	Manually send out of band message	Send the out-of-band message.
ATSuint?	Get register	Query a specific configuration register's value. See Chapter "Registers" for a list of registers.
ATSuint=uint	Set register	Change a configuration register.
AT\$IF=uint	Set TX frequency	Set the output carrier macro channel for Sigfox frames.
AT\$IF?	Get TX frequency	Get the currently chosen TX frequency.
AT\$DR=uint	Set RX frequency	Set the reception carrier macro channel for Sigfox frames.
AT\$DR?	Get RX frequency	Get the currently chosen RX frequency.



Command	Name	Description			
AT\$CW= uint,bit [,uint_opt]	Continuous wave	To run emission tests for Sigfox certification it is necessary to send a continuous wave, i.e. just the base frequency without any modulation. Parameters:			
		Name	Range	Description	Default
		frequency	800000000 – 999999999, 0	Continuous wave frequency in Hz. Use 868130000 for Sigfox or 0 to keep previous frequency.	
		mode	0, 1	Enable or disable carrier wave.	
		power	0-14	dBm of signal	14
AT\$CB= uint_opt,bit	Test mode: TX constant byte		ter specifies the b	ul to send a specific bit p byte to send. Use '-1' for	
		Name	Range	Description	Default
		pattern	0-255, -1	Byte to send. Use '-1' for a (pseudo-) random pattern	
		mode	0, 1	Enable or disable pattern test mode.	
AT\$T?	Get temperature	Measure inte Celsius.	ernal temperature	e and return it in 1/10 th o	f a degree
AT\$V?	Get voltages	Return current voltage and voltage measured during the last transmission in mV.			



Command	Name	Description
AT\$I=uint	Information	Display various product information: 0: Software Name & Version Example Response: AX-Sigfox 1.0.6-ETSI 1: Contact Details Example Response: support@axsem.com 2: Silicon revision lower byte Example Response: 8F 3: Silicon revision upper byte Example Response: 00 4: Major Firmware Version Example Response: 1 5: Minor Firmware Version Example Response: 0 6: Firmware Revision Example Response: 3 7: Firmware Variant (Frequency Band etc. (EU/US)) Example Response: ETSI 8: Firmware VCS Version Example Response: v1.0.2-36 9: SIGFOX Library Version Example Response: DL0-1.4 10: Device ID Example Response: 00012345 11: PAC Example Response: 0123456789ABCDEF
AT\$P=uint	Set power mode	To conserve power, the AX-Sigfox can be put to sleep manually. Depending on power mode, you will be responsible for waking up the AX-Sigfox again! 0: software reset (settings will be reset to values in flash) 1: sleep (send a break to wake up) 2: deep sleep (toggle GPIO9 or RESET_N pin to wake up; the AX-Sigfox is not running and all settings will be reset!)
AT\$WR	Save config	Write all settings to flash (RX/TX frequencies, registers) so that they survive reset/deep sleep or loss of power. Use AT\$P=0 to reset the AX-Sigfox and load settings from flash.



Command	Name	Descript	ion	
AT:Pn?	Get GPIO pin	Return the setting of the GPIO pin n ; n can range from 0 to 9. A character string is returned describing the mode of the pin, followed by the actual value. If the pin is configured as analog pin then the voltage (range 01 V) is returned. The mode characters have the following meaning:		
		Mode	Description	
		0	Pin drives low	
		1	Pin drives high	
		Z	Pin is high impedance input	
		U	Pin is input with pull-up	
		А	Pin is analog input (GPIO pin 03 only)	
		Т	Pin is driven by clock or DAC (GPIO pin 0 and 4 only)	
		The defau	ult mode after exiting reset is U on all GPIO pins.	
AT:Pn=?	Get GPIO pin range	Print a list of possible modes for a pin. The table below lists the response.		
		Pin Modes		
		PO	0,1,Z,U,A,T	
		P1 0,1,Z,U,A		
		P2	0,1,Z,U,A	
		Р3	0,1,Z,U,A	
		P4	0,1,Z,U,T	
		P5	0,1,Z,U	
		P6	0,1,Z,U	
		P7	0,1,Z,U	
		P8	0,1,Z,U	
		P9	0,1,Z,U	
AT:Pn=mode	Set GPIO pin		PIO pin mode. of the modes see the command AT:Pn?	
AT:ADC Pn[-Pn[(1V 10V)]]?	Get GPIO pin analog voltage	allows me pins. In d specified must not result as The GPIO	the voltage applied to a GPIO pin. The command also easurement of the voltage difference across two GPIO differential mode, the full scale range may also be as 1 V or 10 V. Note however that the pin input voltages exceed the range 0VDD_IO. The command returns the fraction of the full scale range (1V if none is specified). It pins referenced should be initialized to analog mode suing this command.	



Command	Name	Description				
AT:SPI[(A B C D)] =bytes	SPI transaction	This command clocks out <i>bytes</i> on the SPI port. The clock frequency is 312.5kHz. The command returns the bytes read on MISO during output. Optionally the clocking mode may be specified (default is A):				
		Mode	Clock Inversion	Clock Phase		
		А	normal	normal		
		В	normal	alternate		
		С	inverted	normal		
		D	inverted	alternate		
			D7 D6 D5		and	
AT:CLK=freq, reffreq	Set clock generator	Output a square wave on the pin(s) set to T mode. The frequency of the square wave is $\frac{freq}{2^{16}} \times reffreq$. Possible values for reffreq are 20000000, 10000000, 5000000, 2500000, 1250000, 625000, 312500, 156250. Possible values if ffreq are 065535.				
AT:CLK=OFF	Turn off clock generator		the clock generator.	<u>'</u>		
AT:CLK?	Get clock generator		e settings of the clock freq and reffreq.	generator. Two numbers are	:	
AT:DAC=value	Set ΣΔ DAC	Output a $\Sigma\Delta$ DAC value on the pin(s) set to T mode. Parameter value may be in the range -3276832767 . The average output voltage is $(\frac{1}{2} + \frac{value}{2^{17}}) \times VDD$. An external low pass filter is needed to get smooth output voltages. The modulation frequency is 20 MHz. A possible low pass filter choice is a simple RC low pass filter with R=10k Ω and C=1 μ F			put w pass	
AT:DAC=OFF	Turn off ΣΔ DAC	Switch off the DAC.				
AT:DAC?	Get ΣΔ DAC	Return the	e DAC value.			





Registers

Number	Name	Description	Default	Range	Unit
300	Out of band period	AX-Sigfox sends periodic static messages to indicate that they are alive. Set to 0 to disable.	24	0-24	hours
302	Power level	The output power of the radio.	14	0-14	dBm



6. Application Information

6.1. Typical Application Diagrams

Typical Sigfox Application Diagram

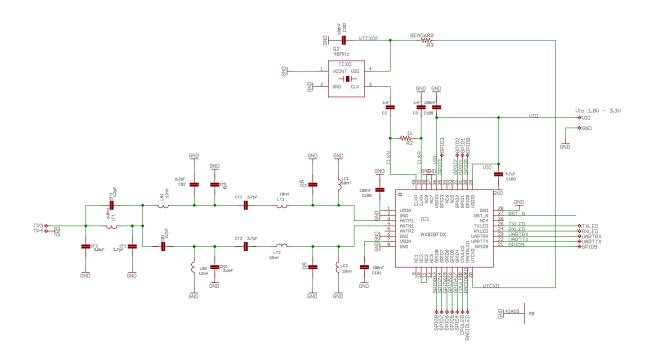


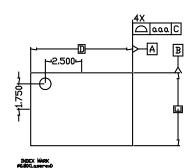
Figure 5 Typical application diagram

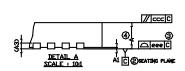
For detailed application configuration and BOM see the AX-Sigfox Application Note: Sigfox Compliant Reference Design.

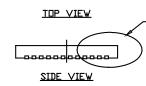


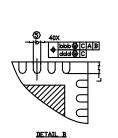
QFN40 Package Information

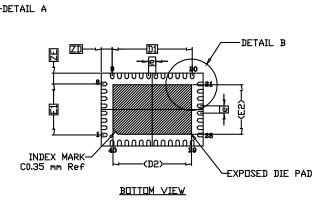
Package Outline QFN40 5x7mm











DIMENSIONA	L REFERE	NCES	Units: mm			
REF.	MIn.	Nom.	Maxi			
Α	0.80	0.90	1.00			
A1	0	0.02	0.05			
A3	- 1	0.20 Ref	•			
D		7.00 BSC	;			
D1	5.50 BSC					
E	5.00 BSC					
E1	3.50 BSC					
e	0.50 BSC					
ZD	0.75 BSC					
75	0.75 BSC					

	Units: mm
REF.	TOLERANCE OF FORM AND POSITION
ممم	0.15
bbb	0.10
C	0.10
ddd	0.05
666	80.0

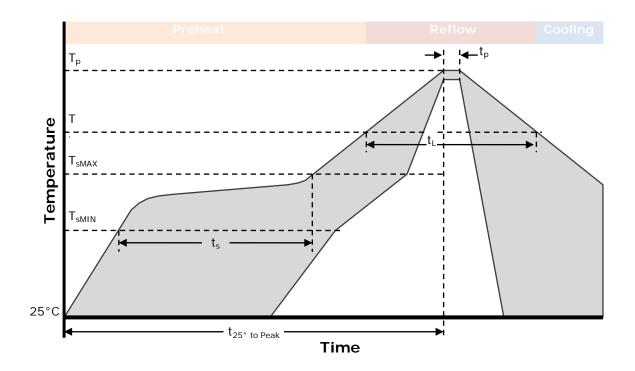
				<u>Unitsi mm</u>
LF REF#.	Symbol	MIn	Nom	Max
FR9020	b	0.18	0.25	0.30
	L	0.30	0.40	0.50
	D2	5,30	5.40	5.50
	E2	3,30	3,40	3.50

Notes

- 'e' represents the basic terminal pitch
- Datum 'C' is the mounting surface with which the package is in contact.
- '3' specifies the vertical shift of the flat part of each terminal from the mounting surface.
- Dimension 'A' includes package warpage.
- Dimension 'b' applies to the metallised terminal and is measured between 0.15 to 0.30 mm from the terminal tip. If the terminal has the optional radius on the other end of the terminal, the dimension 'b' should not be measured in the radius are
- Package dimension take reference from JEDEC MO-220
- RoHS 7.



7.2. QFN40 Soldering Profile



Profile Feature		Pb-Free Process
Average Ramp-Up Rate		3 °C/sec max.
Preheat Preheat		
Temperature Min	T_{sMIN}	150°C
Temperature Max	T_{sMAX}	200°C
Time (T _{sMIN} to T _{sMAX})	t_s	60 – 180 sec
Time 25°C to Peak Temperature	T _{25 ° to Peak}	8 min max.
Reflow Phase		
Liquidus Temperature	T_L	217°C
Time over Liquidus Temperature	t∟	60 – 150 sec
Peak Temperature	t_p	260°C
Time within 5°C of actual Peak Temperature	Тр	20 – 40 sec
Cooling Phase		
Ramp-down rate		6°C/sec max.

Notes:

 $\label{eq:local_equation} \mbox{All temperatures refer to the top side of the package, measured on the package body surface.}$



7.3. QFN40 Recommended Pad Layout

1. PCB land and solder masking recommendations are shown in Figure 6.

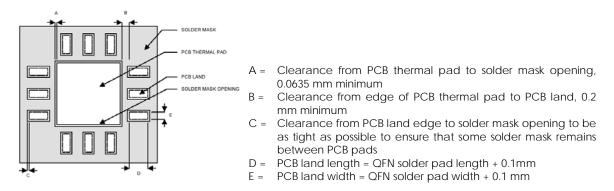


Figure 6 PCB land and solder mask recommendations

- 2. Thermal vias should be used on the PCB thermal pad (middle ground pad) to improve thermal conductivity from the device to a copper ground plane area on the reverse side of the printed circuit board. The number of vias depends on the package thermal requirements, as determined by thermal simulation or actual testing.
- 3. Increasing the number of vias through the printed circuit board will improve the thermal conductivity to the reverse side ground plane and external heat sink. In general, adding more metal through the PC board under the IC will improve operational heat transfer, but will require careful attention to uniform heating of the board during assembly.

7.4. Assembly Process

Stencil Design & Solder Paste Application

- Stainless steel stencils are recommended for solder paste application.
- 2. A stencil thickness of 0.125 0.150 mm (5 6 mils) is recommended for screening.
- 3. For the PCB thermal pad, solder paste should be printed on the PCB by designing a stencil with an array of smaller openings that sum to 50% of the QFN exposed pad area. Solder paste should be applied through an array of squares (or circles) as shown in Figure 7.
- 4. The aperture opening for the signal pads should be between 50-80% of the QFN pad area as shown in Figure 8.
- 5. Optionally, for better solder paste release, the aperture walls should be trapezoidal and the corners rounded.
- 6. The fine pitch of the IC leads requires accurate alignment of the stencil and the printed circuit board. The stencil and printed circuit assembly should be aligned to within + 1 mil prior to application of the solder paste.
- 7. No-clean flux is recommended since flux from underneath the thermal pad will be difficult to clean if water-soluble flux is used.



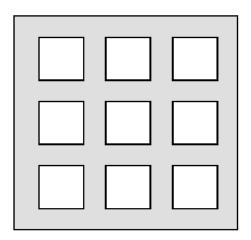


Figure 7 Solder paste application on exposed pad

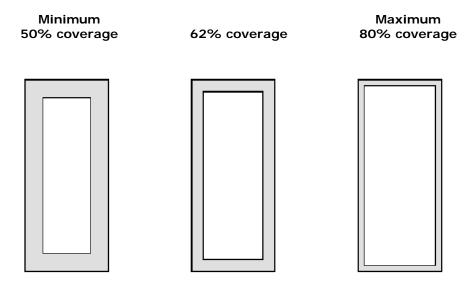


Figure 8 Solder paste application on pins



Device Versions

Version	Device Marking	AT\$I=0	AT\$I=2	AT\$I=3
1	AX-Sigfox-1 or AX8052F143-2	AX-Sigfox 1.0.6-ETSI	0x8F	0x51

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